



SOT2074-1

XQFN12, extremely thin quad flat package, no leads, 12 terminals, 0.4 mm pitch, 1.75 mm x 2.2 mm x 0.5 mm body

8 December 2020

Package information

1 Package summary

Terminal position code	Q (quad)
Package type descriptive code	XQFN12
Package style descriptive code	XQFN (extremely thin quad flatpack; no leads)
Mounting method type	S (surface mount)
Issue date	17-07-2020
Manufacturer package code	98ASA01665D

Table 1. Package summary

Parameter	Min	Nom	Max	Unit
package length	1.74	1.75	1.76	mm
package width	2.1	2.2	2.3	mm
package height	-	-	0.5	mm
nominal pitch	-	0.4	-	mm
actual quantity of termination	-	12	-	



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2 Package outline

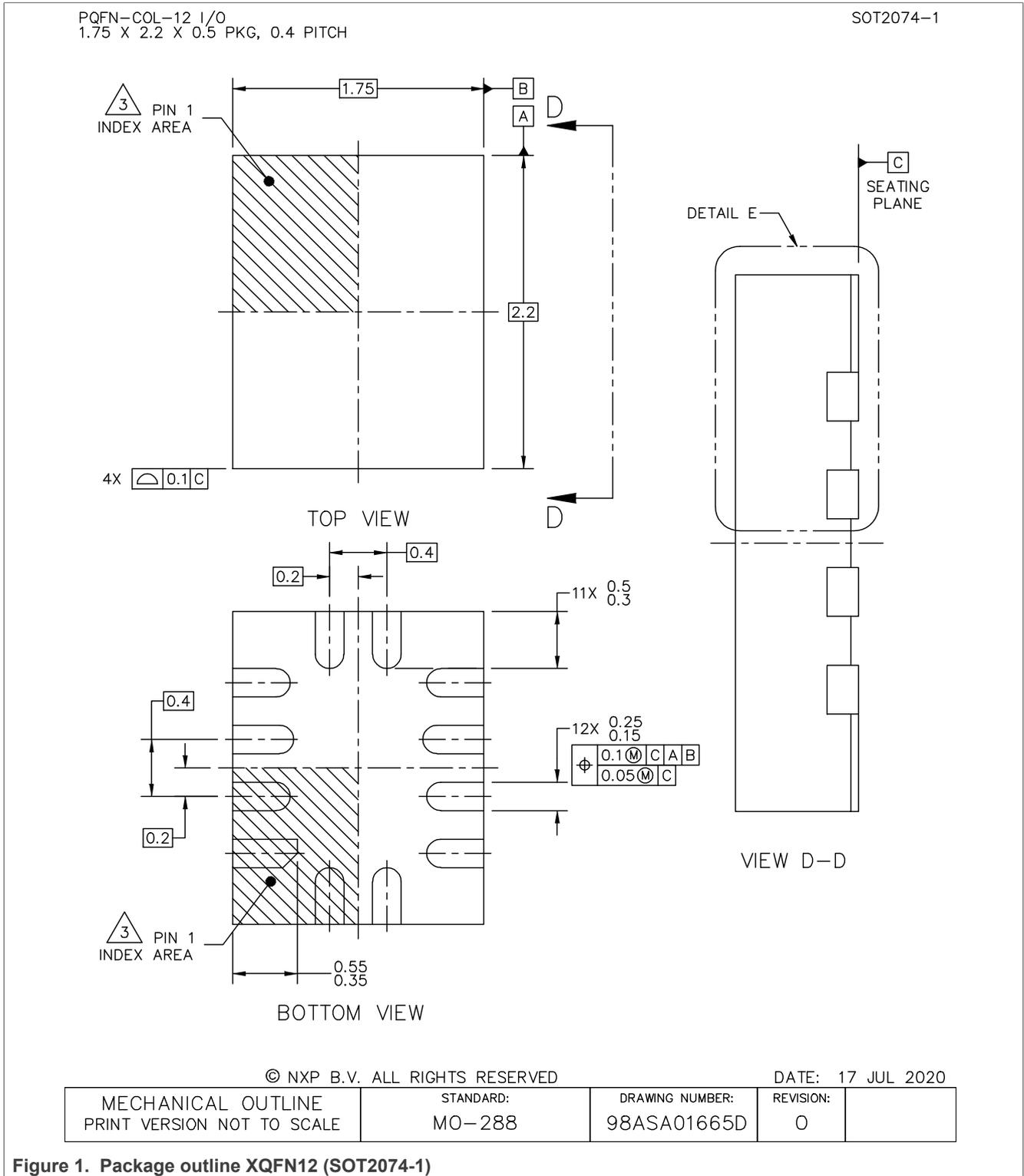


Figure 1. Package outline XQFN12 (SOT2074-1)

XQFN12, extremely thin quad flat package, no leads, 12 terminals, 0.4 mm pitch, 1.75 mm x 2.2 mm x 0.5 mm body

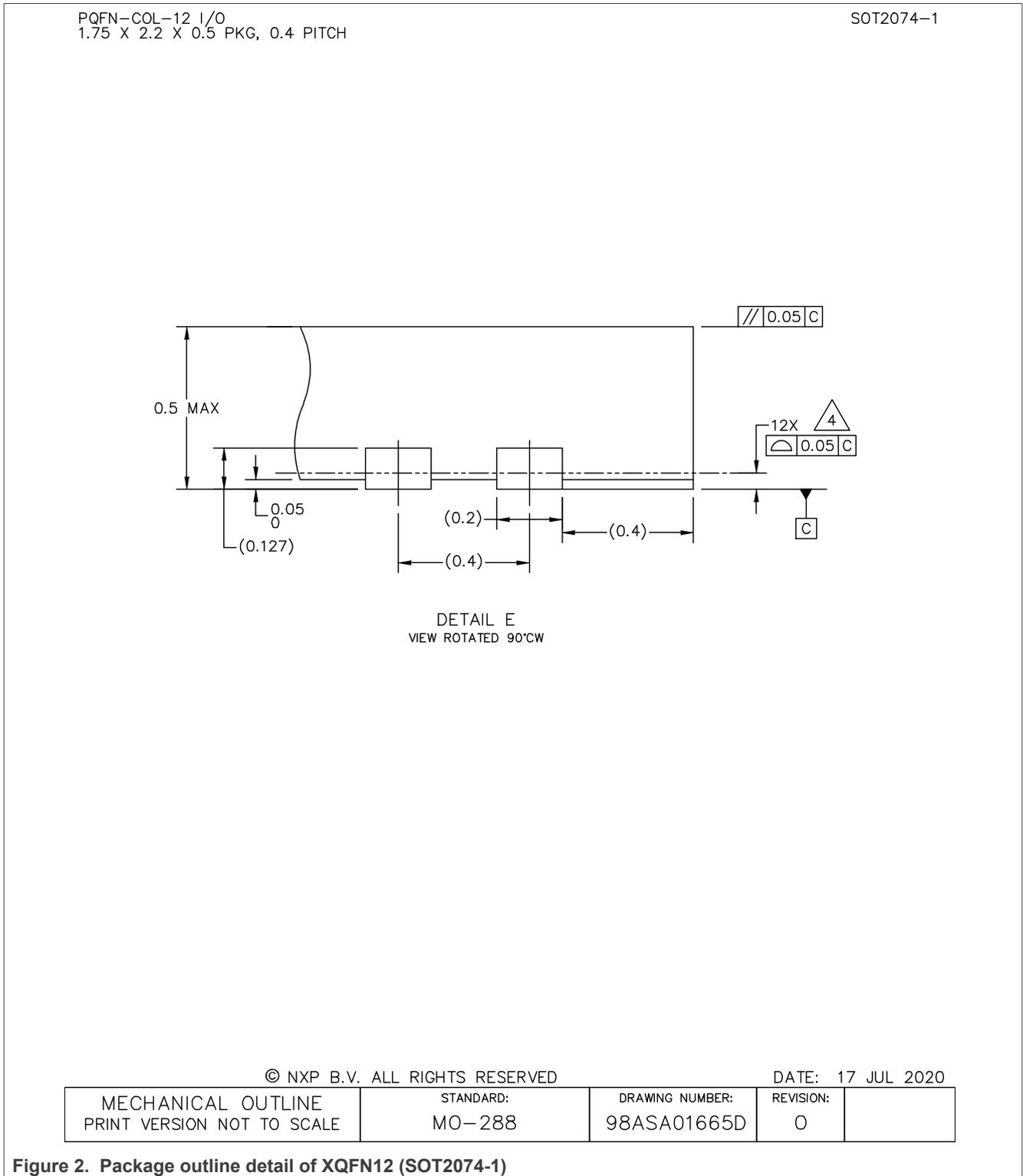
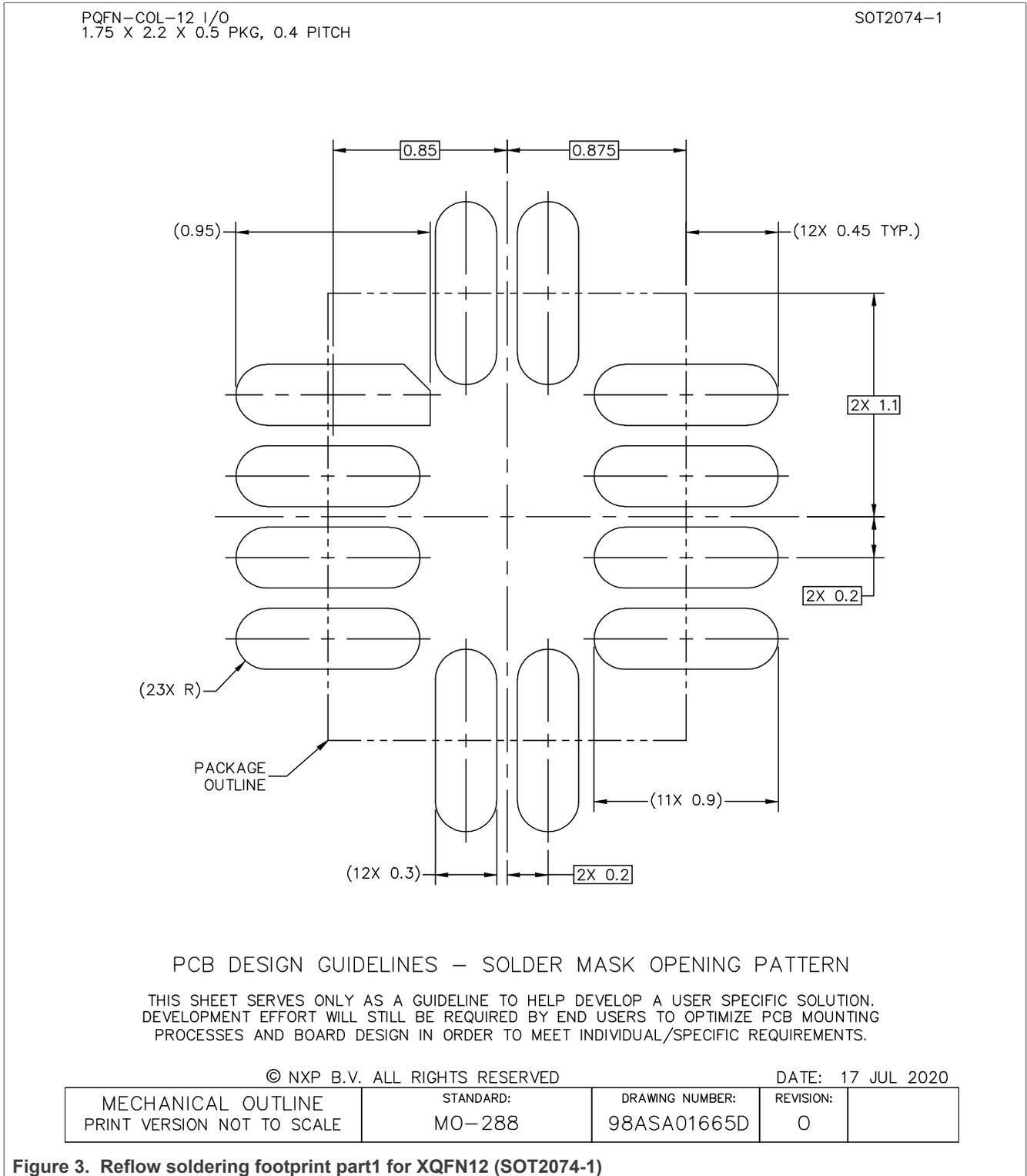


Figure 2. Package outline detail of XQFN12 (SOT2074-1)

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3 Soldering



XQFN12, extremely thin quad flat package, no leads, 12 terminals, 0.4 mm pitch, 1.75 mm x 2.2 mm x 0.5 mm body

PQFN-COL-12 I/O
1.75 X 2.2 X 0.5 PKG, 0.4 PITCH

SOT2074-1

NOTES:

1. ALL DIMENSIONS ARE IN MILLIMETERS.
2. DIMENSIONING AND TOLERANCING PER ASME Y14.5M-1994.
3. PIN 1 FEATURE SHAPE, SIZE AND LOCATION MAY VARY.
4. COPLANARITY APPLIES TO LEADS.
5. MIN. METAL GAP SHOULD BE 0.15 MM.

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MECHANICAL OUTLINE PRINT VERSION NOT TO SCALE	STANDARD: MO-288	DRAWING NUMBER: 98ASA01665D	REVISION: 0	
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Figure 6. Package outline note XQFN12 (SOT2074-1)

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4 Legal information

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